



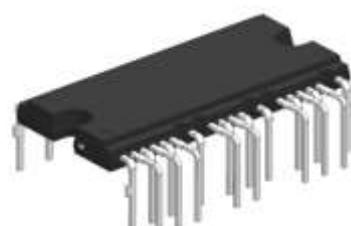
# SPE10S60H-A

## 主要参数 MAIN CHARACTERISTICS

600V/10A 3相全桥驱动	
V <sub>CES</sub>	600V
I <sub>C</sub>	10A
V <sub>Iso</sub>	1500V

用途	APPLICATIONS
● 风机	● Fan motor
● 水泵	● Water pump
● 冰箱	● Refrigerator

## 封装 Package



## 产品特性

- 600V/10A 三相逆变器，内置低损耗沟道栅-场截止型 IGBT。
- 信号高电平有效，兼容 3.3V 和 5V 的 MCU。
- 内置自举二极管。
- 内置欠压保护、过流保护、过温保护。
- 使能关断功能。
- 恒流温度检测输出。

## FEATURES

- 600V/10A three-phase inverter with built-in low-loss trench-gate-field stop IGBT.
- Signal high level active, compatible with 3.3v and 5V MCU.
- Built-in bootstrap diode.
- Built-in undervoltage protection、Over current protection、Over temperature protection.
- Shut-Down Input.
- Constant current temperature detection output.

## 订货信息 ORDER MESSAGE

订 货 料 号 Order number	产 品 信 息 Product information			
	无卤-条管 Halogen-Free-Tube	无卤-编带 Halogen-Free-Reel	印 记 Marking	封 装 Package
2A01-0892	SPE10S60H-A	N/A	SPE10S60H-A	DIP26-FP

## 模块分布示意图 Module distribution diagram

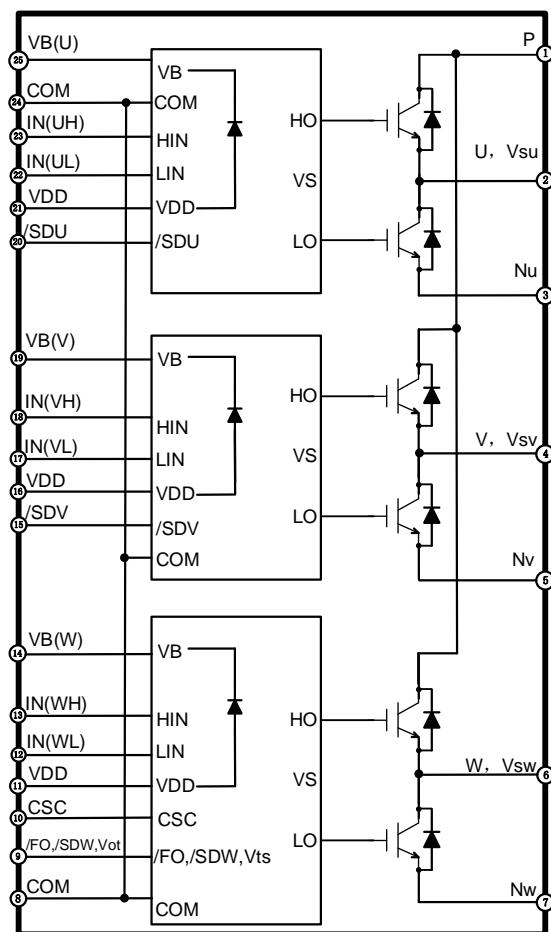


图 1：模块内部电路示意图

Fig 1: Internal circuit

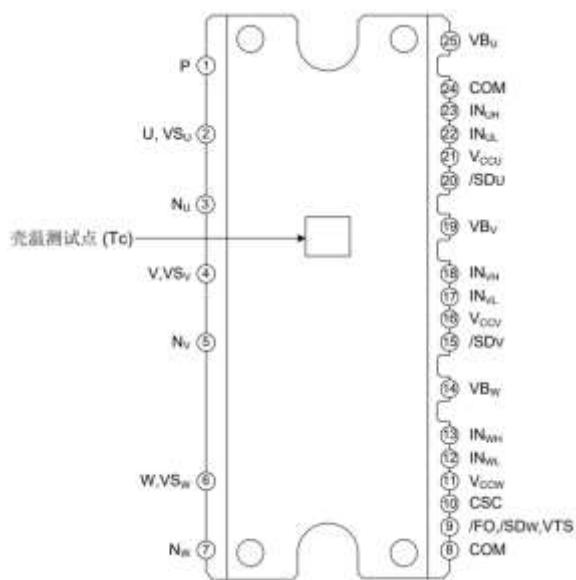


图 2：模块引脚分布示意图

Fig 2: Distribution of pin



引脚编号 Number	引脚名称 Name	引脚描述 Description
1	P	逆变器直流输入端子 DC input terminal of inverter
2	U, VS <sub>U</sub>	U 相输出和 U 相高侧驱动偏置电压地 Output for U-Phase & Bias Voltage Ground for U-phase High-Side Driving
3	N <sub>U</sub>	U 相下臂 IGBT 发射极端子 U phase lower arm IGBT emitter terminal
4	V, VS <sub>V</sub>	V 相输出和 V 相高侧驱动偏置电压地 Output for V-Phase & Bias Voltage Ground for V-phase High-Side Driving
5	N <sub>V</sub>	V 相下臂 IGBT 发射极端子 V phase lower arm IGBT emitter terminal
6	W, VS <sub>W</sub>	W 相输出和 W 相高侧驱动偏置电压地 Output for W-Phase & Bias Voltage Ground for W-phase High-Side Driving
7	N <sub>W</sub>	W 相下臂 IGBT 发射极端子 W phase lower arm IGBT emitter terminal
8	COM	公共电源接地 GND Common Supply Ground
9	/FO, /SDW, VOT	故障输出, W 相输入关闭, 温度输出 Fault Output, Shut-Down Input for W Phase, Temperature Output
10	CSC	过流和短路保护关闭输入端子 Shut Down Input for Over Current and Short Circuit Protection
11	V <sub>CCW</sub>	控制电源端子 Control power terminal
12	IN <sub>WL</sub>	W 相下臂控制信号输入端子 W phase lower arm control signal input terminal
13	IN <sub>WH</sub>	W 相上臂控制信号输入端子 W phase upper arm control signal input terminal
14	VB <sub>W</sub>	W 相上臂驱动电源端子 W phase upper arm drive power terminal
15	/SD <sub>V</sub>	V 相输入关闭 Shut-Down Input for V Phase
16	V <sub>CCV</sub>	控制电源端子 Control power terminal
17	IN <sub>VL</sub>	V 相下臂控制信号输入端子 V phase lower arm control signal input terminal
18	IN <sub>VH</sub>	V 相上臂控制信号输入端子 V phase upper arm control signal input terminal
19	VB <sub>V</sub>	V 相上臂驱动电源端子 V phase upper arm drive power terminal
20	/SD <sub>U</sub>	U 相输入关闭 Shut-Down Input for U Phase
21	V <sub>CCU</sub>	控制电源端子 Control power terminal
22	IN <sub>UL</sub>	U 相下臂控制信号输入端子 U-phase lower arm control signal input terminal
23	IN <sub>UH</sub>	U 相上臂控制信号输入端子 U-phase upper arm control signal input terminal
24	COM	公共电源接地 GND Common Supply Ground
25	VB <sub>U</sub>	U 相上臂驱动电源端子 U-phase upper arm drive power terminal

图 3: 模块引脚功能定义表

Fig 3: Pin function



**最大额定值** ( $T_j = 25^\circ\text{C}$ , 除非特殊说明)

**Absolute Maximum Ratings** ( $T_j = 25^\circ\text{C}$ , Unless otherwise Specified)

#### 逆变部分 Inverter Part

记号 Symbol	参数 Parameter	条件 Condition	额定值 Ratings	单位 Units
$V_{PN}$	电源电压 Power supply voltage	应用于 P- NU, NV, NW 之间 Applied between P- NU, NV, NW	450	V
$V_{PN(\text{Surge})}$	电源电压 (含浪涌) Power supply voltage (including surge)	应用于 P- NU, NV, NW 之间 Applied between P- NU, NV, NW	500	V
$V_{CES}$	集电极-发射极之间电压 Collector emitter Voltage of Each IGBT	-	600	V
$\pm I_C$	集电极电流 Each IGBT Current, Continuous	$T_C = 25^\circ\text{C}$ , $T_C = 100^\circ\text{C}$	10 5	A
$\pm I_{CP}$	集电极电流 (峰值) Each IGBT Pulse Current, Peak	$T_C = 25^\circ\text{C}$ , 脉冲宽度小于 1ms $T_C = 25^\circ\text{C}$ , Less than 1mS	20	A
$P_C$	集电极功耗 Maximum Power Dissipation	$T_C = 25^\circ\text{C}$ , 单晶片 $T_C = 25^\circ\text{C}$ , Each IGBT	26	W
$T_J$	结温 Junction Temperature	(见备注 1) Note1	-40~150	°C

#### 控制部分 Control Part

记号 Symbol	参数 Parameter	条件 Condition	额定值 Ratings	单位 Units
$V_{CC}$	控制电源电压 Control Supply Voltage	VCC-COM 之间 Applied between VCC and COM	20	V
$V_{BS}$	高侧控制电压 High-side Bias Voltage	VB-VS 之间 Applied between VB and VS	20	V
$V_{IN}$	输入信号电压 Input Signal Voltage	VIN-COM 之间 Applied between VIN and COM	-0.3~ $V_{CC}$ +0.3	V

#### 整个系统 Total System

记号 Symbol	参数 Parameter	条件 Condition	额定值 Ratings	单位 Units
$V_{PN(\text{PROT})}$	自我保护电源电压限制 Self-protecting power supply voltage limit	$V_{CC}=V_{BS}=13.5\text{V}\sim16.5\text{V}$ , $T_J=125^\circ\text{C}$ , 非重复性, <2us	400	V
$T_c$	模块壳体工作温度 Module shell temperature	-	-20~100	°C
$T_{STG}$	贮存温度 Storage Temperature	-	-40~125	°C
$V_{ISO}$	绝缘耐压 Isolation Voltage	60Hz, 正弦, AC 1 分钟, 连接管脚到散热器 60Hz, Sinusoidal, AC 1 min, between pins and heat-sink plate	1500	Vrms
$T$	安装力矩 Mounting Torque	安装螺丝: M3	0.6	N.m

备注 1: IPM 功率晶片最大额定结温为  $150^\circ\text{C}$  (@表面温度  $T_C \leq 100^\circ\text{C}$ )。然而, 为了确保 IPM 运行安全, 结温应限定

于  $T_j(\text{av}) \leq 125^\circ\text{C}$  (@表面温度  $T_c \leq 100^\circ\text{C}$ )。



Note 1: The maximum rated junction temperature of the IPM power chip is 150° C (@surface temperature TC ≤ 100° C). However, to ensure safe operation of the IPM, the junction temperature should be limited to T<sub>j(av)</sub> ≤ 125° C (@surface temperature TC ≤ 100° C)

### 热阻 Thermal Resistance

记号 Symbol	参数 Parameter	条件 Condition	额定值 Ratings	单位 Units
R <sub>th(j-c)Q</sub>	结到外壳的热阻 Junction to Case Thermal resistance	逆变器工作条件下的单个IGBT Each IGBT	4.8	°C/W
R <sub>th(j-c)F</sub>	结到外壳的热阻 Junction to Case Thermal resistance	逆变器工作条件下的单个FRD Each FRD	6.0	°C/W

备注 2: 关于壳体温度 (TC) 的测量点, 参见图 2。

Note 2: For the measurement point of shell temperature (TC), see Figure 2.

### 电气特性 (T<sub>j</sub>=25°C, 除非特殊说明)

Electrical Characteristics (T<sub>J</sub>=25°C, Unless Otherwise Specified)

#### 逆变部分 Inverter Part

记号 Symbol	参数 Parameter	条件 Condition		最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
V <sub>CE(SAT)</sub>	集电极-发射极间饱和电压 Collector - emitter saturation voltage	V <sub>CC</sub> =V <sub>BS</sub> =15V, V <sub>IN</sub> =5V	I <sub>C</sub> =10A, T <sub>J</sub> =25°C,	-	1.6	2.2	V
			I <sub>C</sub> =10A, T <sub>J</sub> =125°C,	-	2.0	-	
V <sub>F</sub>	FRD正向电压 FRD Forward voltage	V <sub>IN</sub> = 0V, IC=-10A,		-	1.6	2.2	V
I <sub>CES</sub>	集电极-发射极间漏电流 Collector emitter leakage current	V <sub>CE</sub> =V <sub>CES</sub>		-	-	250	uA
t <sub>ON</sub>	开关时间 (备注3) Switching Times(Note 3)	V <sub>PN</sub> = 300 V, V <sub>D</sub> = V <sub>DB</sub> = 15 V, I <sub>C</sub> =10 A V <sub>IN</sub> = 0 V ↔ 5 V, 电感负载 / Inductive Load		-	310	-	nS
t <sub>C(ON)</sub>				-	70	-	
t <sub>OFF</sub>				-	360	-	
t <sub>C(OFF)</sub>				-	70	-	
t <sub>rr</sub>				-	80	-	

备注 3: t<sub>ON</sub> 和 t<sub>OFF</sub> 包括驱动 IC 内部传输延迟时间。t<sub>C(ON)</sub> 和 t<sub>C(OFF)</sub> 是 IGBT 自身被内部给定门极驱动条件下的开关时间。详见图 3。

Note 3: t<sub>ON</sub> and t<sub>OFF</sub> include the internal propagation delay time of the driver IC. t<sub>C(ON)</sub> and t<sub>C(OFF)</sub> are the switching times of the IGBT itself driven by the internally given gate. See Figure 3 for details.



## 控制部分 Control Part

记号 Symbol	参数 Parameter	条件 Condition		最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit	
I <sub>QCC</sub>	VCC 静态电流 Quiescent VCC Supply Current	VCC=15V VIN=5V	VCC-COM 之间 Applied between VCC and COM	-	-	500	uA	
I <sub>QBS</sub>	VBS 静态电流 Quiescent VBS Supply Current	VBS=15V VIN=0V	VB(U)-U, VB(V)-V, VB(W)-W 之间 Applied between VB(U)-U, VB(V)-V, VB(W)-W	-	-	200	uA	
V <sub>FOH</sub>	故障输出电压 Fault Out Voltage	VSC=0V, /FO Circuit: 6.8K to 5V pull-up	VSC=1V, /FO Circuit: 6.8K to 5V pull-up	4.2	-	-	V	
V <sub>FOL</sub>				-	-	0.5		
V <sub>SC(ref)</sub>	短路跳闸阈值 Short-Circuit Trip Level	V <sub>cc</sub> =15 V		0.40	0.45	0.51	V	
U <sub>VCCD</sub>	低侧欠压保护(图 5) Low-Side Under-Voltage Protection (Fig 5)	检测电平 Detection Level		11.2	12.2	13.2	V	
U <sub>VCCR</sub>		复位电平 Reset Level		11.8	12.8	13.5	V	
U <sub>VBSD</sub>	高侧欠压保护(图 6) High-Side Under-Voltage Protection (Fig 6)	检测电平 Detection Level		9.8	10.8	11.8	V	
U <sub>VBSR</sub>		复位电平 Reset Level		10.5	11.5	12.5	V	
T <sub>FO</sub>	故障输出脉冲宽度 Fault-Out Pulse Width			20	-	-	uS	
I <sub>FO</sub>	温度输出电流 Fault current Temperature Sensing (note4)	T <sub>j</sub> =25°C		-	82.5	-	uA	
		T <sub>j</sub> =75°C		-	207.5	-	uA	
T <sub>FO</sub>	温度输出电压 Fault Voltage Temperature Sensing	HVIC 温度=25°C, 上拉6.8KΩ电阻到5V		-	4.18	-	V	
		HVIC 温度=75°C, 上拉6.8KΩ电阻到5V		-	2.93	-	V	
V <sub>FSDR</sub>	使能关断复位电平 Shut-down Reset level	SDx-COM		1.7	2.2	2.5	V	
V <sub>FSDD</sub>	使能关断阈值电压 Shut-down Detection level	SDx-COM		0.8	1.3	1.5	V	
V <sub>IH</sub>	导通阈值电压 ON Threshold Voltage	逻辑高电平 Logic high level	施加在V <sub>IN</sub> 和COM之间 Applied between V <sub>IN</sub> and COM	-	-	2.5	V	
V <sub>IL</sub>	关断阈值电压 OFF Threshold Voltage	逻辑低电平 Logic low level		0.8	-	-	V	

备注 4: IPM 的温度输出电流特性曲线请参考图 4.2, 图 4.2 曲线是以 6.8KΩ上拉电阻至 5V 和以 4.7 KΩ上拉电阻至 3.3V 测试结果。

Note 4: Please refer to figure 4.2 for the temperature output current characteristic curve of IPM. The curve in Figure 4.2 shows the test results of 6.8 KΩ pull-up resistance to 5V and 4.7 KΩ pull-up resistance to 3.3V.

## 推荐工作条件 Recommended Operating Conditions

记号 Symbol	参数 Parameter	条件 Condition	最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
$V_{PN}$	电源电压 Supply Voltage	施加在P和N之间 Between P and N	-	300	400	V
$V_{CC}$	控制电源电压 Control Supply Voltage	施加在 $V_{CC}$ 和 COM 之间 Between $V_{CC}$ and COM	13.5	15.0	16.5	V
$V_{BS}$	高端偏压 High-Side Bias Voltage	施加在 $V_B$ 和 $V_S$ 之间 Between $V_B$ and $V_S$	13.5	15.0	16.5	V
$d_{VCC}/dt$ , $d_{VBS}/dt$	控制电源波动 Control power fluctuation	-	-1	-	1	V/us
$t_{dead}$	防止桥臂直通的死区时间 Blanking Time for Preventing Arm-Short	$V_{CC} = V_{BS} = 13.5 \sim 16.5 \text{ V}, T_j \leq 150^\circ\text{C}$	1.0	-	-	us
$P_{WIN(ON)}$	输入信号最小开启脉宽 Minimum On pulse width of input signal	-	0.7	-	-	us
$P_{WIN(off)}$	输入信号最小关闭脉宽 Minimum Off Pulse Width of Input Signal	-	0.7	-	-	us
$F_{PWM}$	PWM 开关频率 PWM Switching Frequency	$T_j \leq 150^\circ\text{C}$	-	-	20	KHz

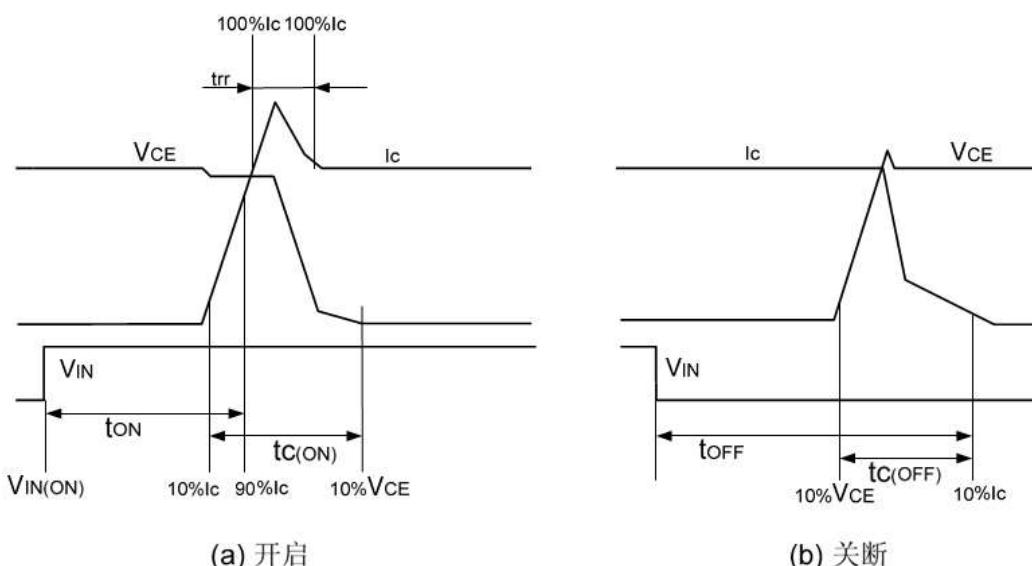
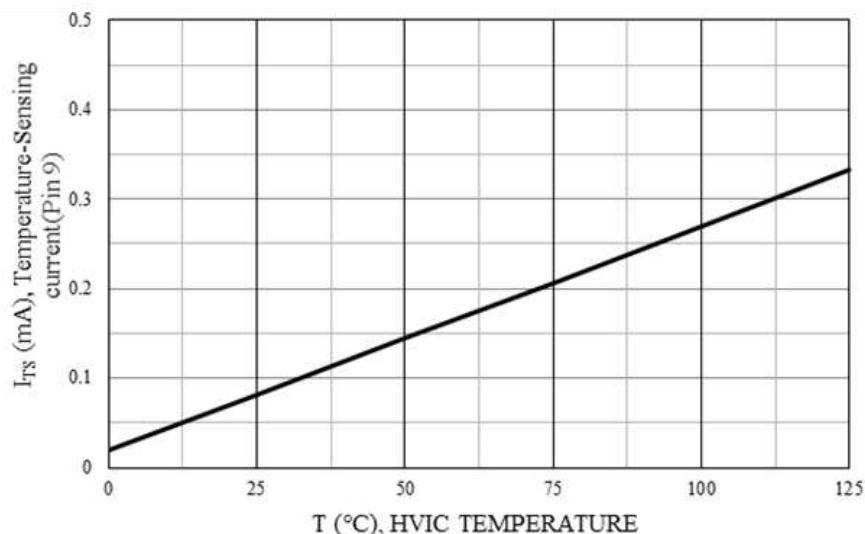
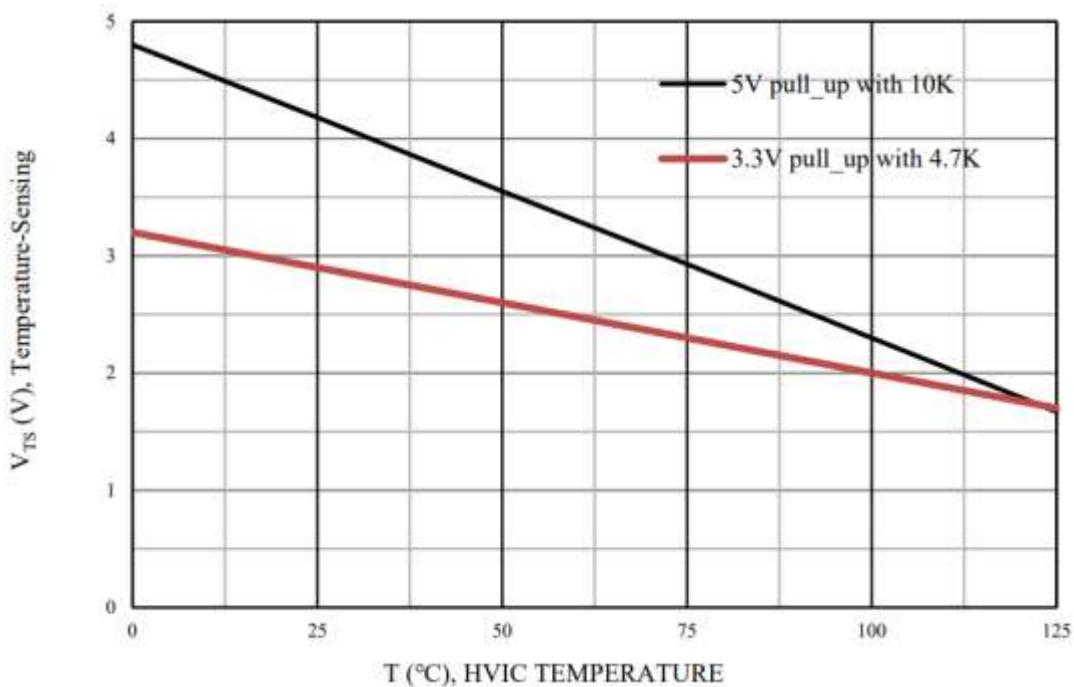


图 3: 开关时间定义  
Fig 3: Switching Time Definition

**IC 温度输出的电流-温度曲线 I-T curve of temperature output of IC****图 4.1: HVIC 温度检测输出温度—电流曲线****Fig 4.1: Curves of HVIC Temperature-Current Output****图 4.2: HVIC 温度检测输出温度—电压曲线****Fig 4.2: Curves of HVIC Temperature detection-voltage curve**

## 保护功能时序图 Time Charts of Protective Function

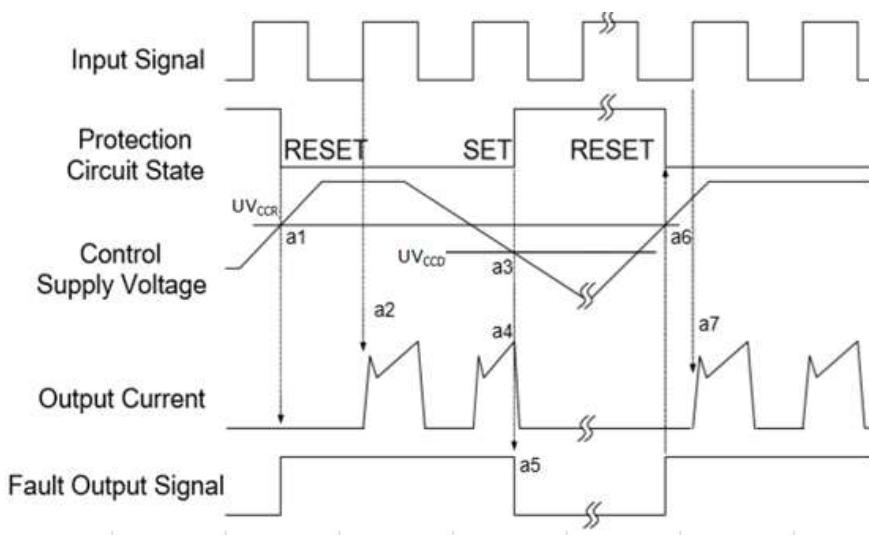


图 5：欠压保护时序图(低侧)

Fig 5: Undervoltage protection sequence diagram (low side)

a1 :电源电压上升: 电压上升至  $UV_{CCR}$ ,当下一个输入信号到来时电路开始工作;

a1 : Control supply voltage rises: after the voltage rises  $UV_{CCR}$ , the circuits start to operate when next input is applied.

a2: 正常运行: IGBT 开启并加载电流。

a2: Normal operation: IGBT turns on and loads current.

a3: 欠压检测点( $UV_{CCD}$ )。

a3: Undervoltage detection point ( $UV_{CCD}$ ).

a4: 不管输入是什么信号, IGBT 都是关闭状态。

a4: No matter what signal is input, the IGBT is off.

a5: 故障输出开启。

a5: Fault output is on.

a6: 欠压恢复( $UV_{CCR}$ )。

a6: Undervoltage recovery ( $UV_{CCR}$ ).

a7: 正常运行: IGBT 导通并加载负载电流。

a7: Normal operation: IGBT is turned on and load current is loaded.

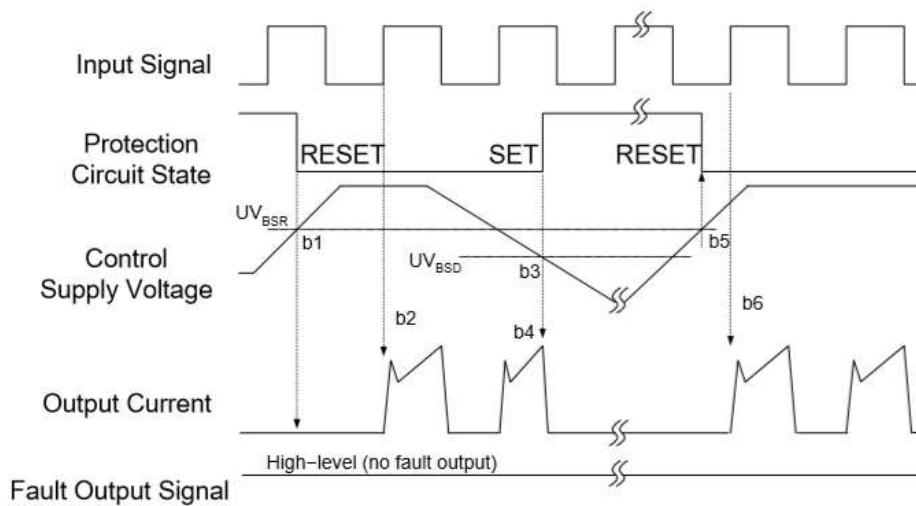


图 6: 欠压保护时序图(高侧)

Fig 6: Undervoltage protection sequence diagram (High side)

- b1 : 电源电压上升: 当该电压上升到欠压恢复点, 在下一个欠压信号被执行前该线路将启动运行。  
b1: Power supply voltage rise: When the voltage rises to the undervoltage recovery point, the line will start running before the next undervoltage signal is executed.  
b2 : 正常运行: IGBT 导通并加载负载电流。  
b2: Normal operation: IGBT is turned on and load current is applied.  
b3 : 欠压检测 ( $UV_{BSD}$ )。  
b3: Undervoltage detection ( $UV_{BSD}$ ).  
b4 : 不管输入是什么信号, IGBT 都是关闭状态。  
b4: No matter what signal is input, IGBT is off.  
b5 : 欠压恢复( $UV_{BSR}$ )。  
b5: Undervoltage recovery ( $UV_{BSR}$ ).  
b6 : 正常运行: IGBT 导通并加载负载电流。  
b6: Normal operation: IGBT is turned on and load current is applied.

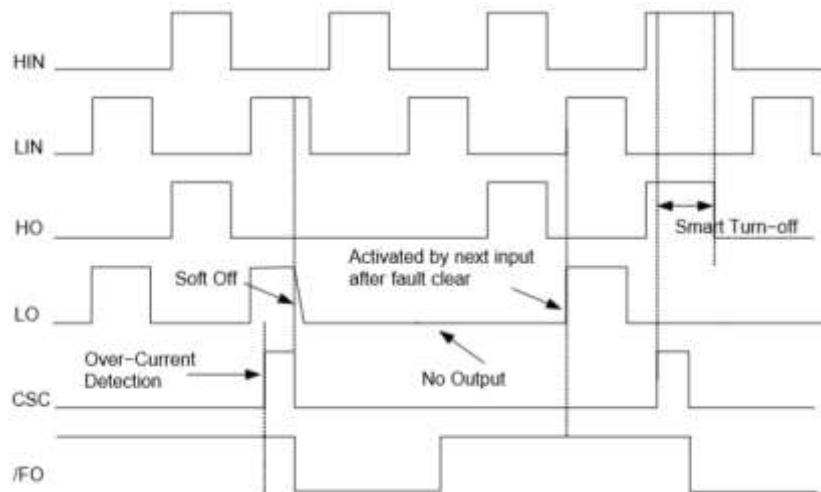


图 7: 过流保护时序

Fig 7: Fault-Out Function by Over Current Protection

HIN :高侧输入信号;

HIN : High-side Input Signal

LIN : 低侧输入信号;

LIN : Low-side Input Signal

HO : 高侧输出信号;

HO : High-Side Output Signal

LO : 低侧输出信号;

LO : Low-Side Output Signal

CSC :过流侦测信号;

CSC : Over Current Detection Input

/FO:故障输出信号

/FO : Fault Out Function

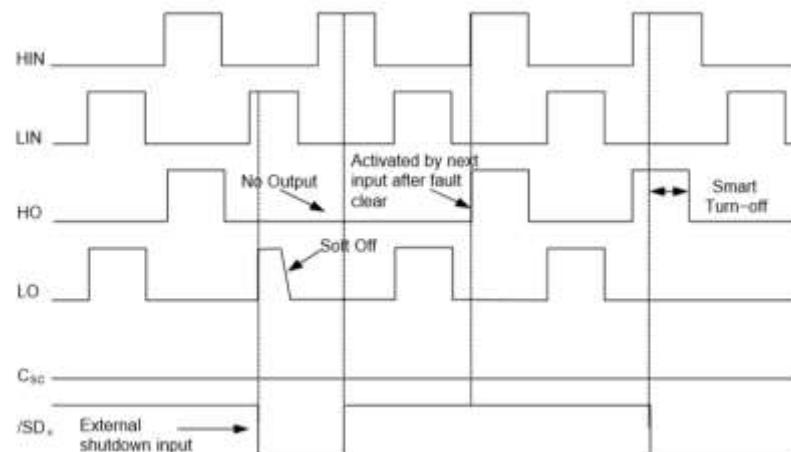


图 8. 外部关断功能时序

Figure 8. Shutdown Input Function by External Command

HIN :高侧输入信号;

HIN : High-side Input Signal

LIN : 低侧输入信号;

LIN : Low-side Input Signal

HO : 高侧输出信号;

HO : High-Side Output Signal

LO : 低侧输出信号;

LO : Low-Side Output Signal

CSC :过流侦测信号;

CSC : Over Current Detection Input

/SDx:外部关断输入信号

/SDx : Shutdown Input Function

输入输出接口电路 **Input/output interface circuit**

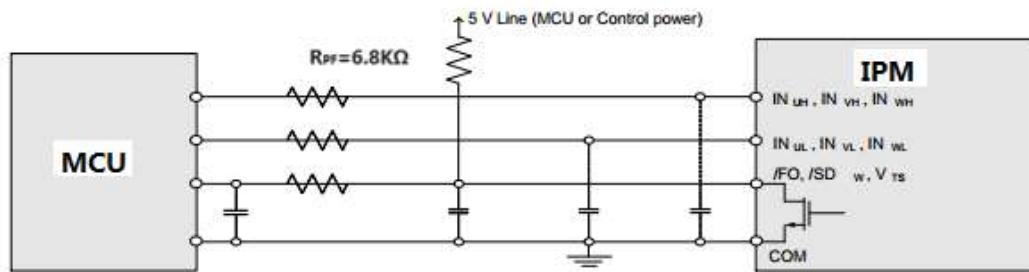


图 9. 推荐的 MCU I/O 接口电路

Figure 9: Recommended MCU input and output interface circuit

备注 5: 由于 PWM 的控制方式和实际应用电路的阻抗及线路板的阻抗, RC 去耦可能会有变化。

Note 5 : Due to the PWM control method and the impedance of the actual application circuit and the impedance of the circuit board, RC decoupling may change.

### 应用电路 Application Circuit

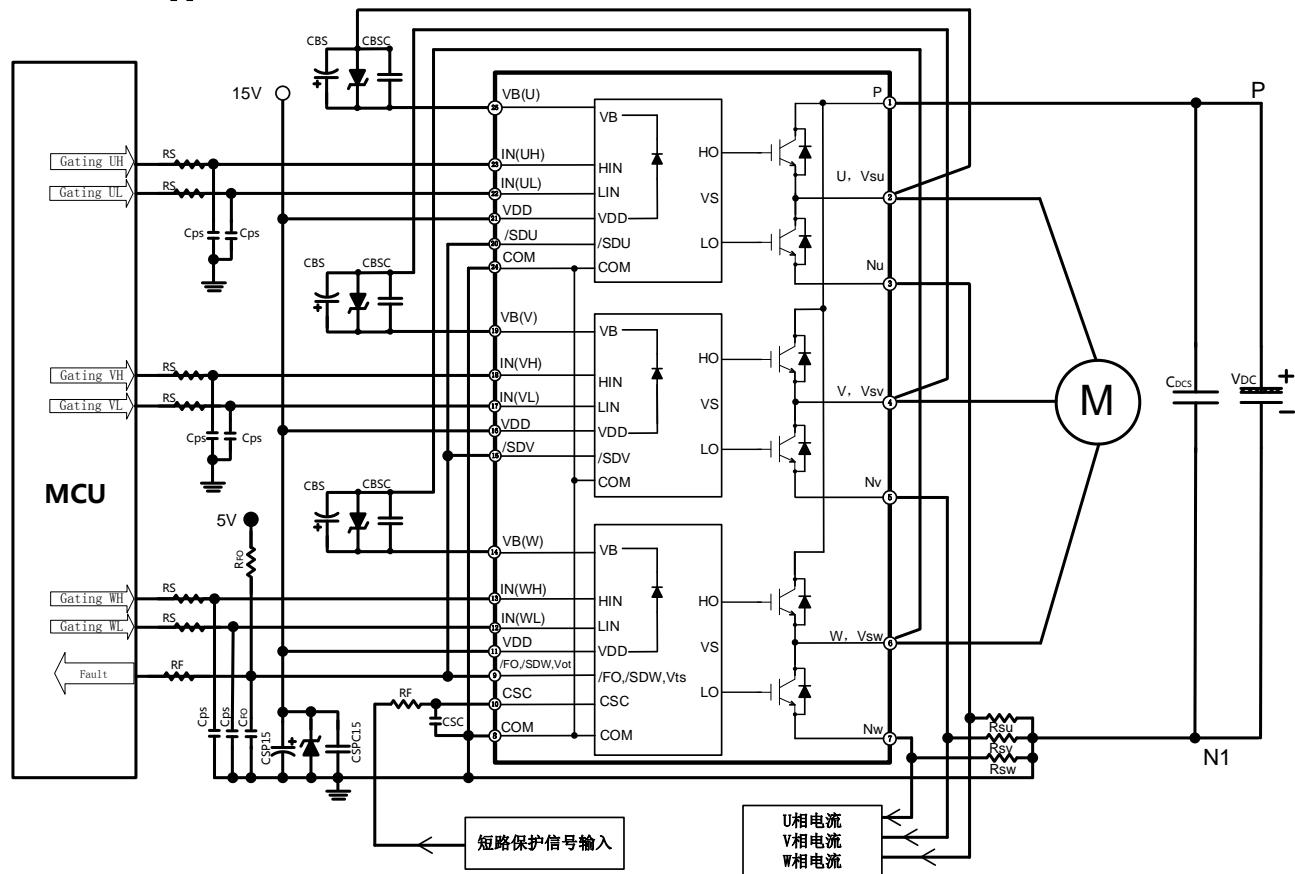


图 10: 典型应用电路图

Fig 10: Example of Application Circuit

备注 6: .关于引脚的位置请参阅图 1.

Note 6: Refer to figure 1 for pin location.



备注 7:为避免故障，各输入接线应尽可能短。

Note 7:To avoid malfunction, the wiring of each input should be as short as possible

备注 8:为防止浪涌损坏，PN 之间建议增加一个高频非感性平缓电容（ $0.1\mu F \sim 0.22\mu F$ ），电容的连线要尽量短。

Note 8:To prevent surge destruction, it is recommended to add a high-frequency non inductive smoothing capacitor ( $0.1\mu F \sim 0.22\mu F$ ) between PN, and the wiring of the capacitor should be as short as possible.

备注 9:输入信号高电平有效，在 HVIC 每个通道的输入端都有一个下拉电阻连接到地；建议在输入端增加 RC 滤波电路来防止输入信号振荡。

Note 9: The high level of the input signal is effective, and a pull-down resistor is connected to the ground at the input terminals of eachchannel of HVIC; It is suggested to add RC filter circuit at the input terminals to prevent input signal oscillation.

备注 10:所有电容的位置尽可能的靠近 IPM。

Note 10: Position all capacitors as close to IPM as possible.

备注 11:控制地线和电源地线要连接在一个点，走线尽量短；

Note 11:The control ground wire and power ground wire shall be connected at one point, and the wiring shall be as short as possible;

备注 12.在短路保护电路，请选择时间常数在  $1.5 \sim 2\mu s$  范围内的 RF 和 CSC,同时 RF 和 CSC 周边的接线都应尽量短，RF 接线应靠近分流电阻；

Note 12:In the short-circuit current protection circuit, please select the RF CSC time constant in the range  $1.5 \sim 2\mu s$ ,At the same time, the wiring around RF and CSC shall be as short as possible, and RF wiring shall be close to shunt resistance;

备注 13./FO,/SD 的连线尽可能短。

Note 13:/FO and /SD must be connected as short as possible.



## 外形封装图 Detailed Package Outline Drawings

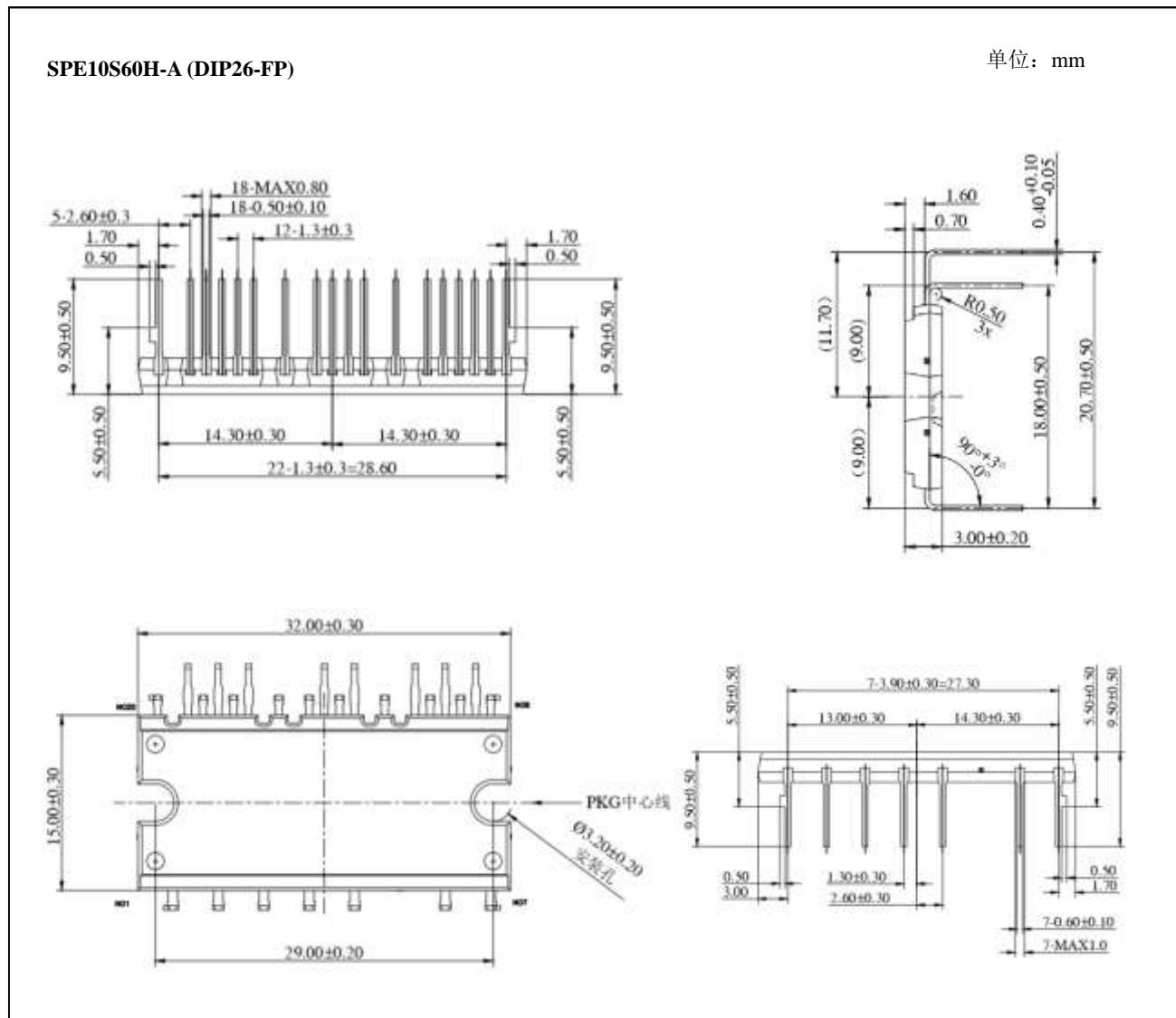


图 11: SPE10S60H-A 封装外形图

Fig 11: SPE10S60H-A Package Outline Drawings



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## 联系方式

### 吉林华微电子股份有限公司

公司地址：吉林省吉林市深圳街 99 号

邮编：132013

总机：86-432-64678411

传真：86-432-64665812

网址：[www.hwdz.com.cn](http://www.hwdz.com.cn)

## CONTACT

### JILIN SINO-MICROELECTRONICS CO., LTD.

ADD: No.99 Shenzhen Street, Jilin City, Jilin Province, China.

Post Code: 132013

Tel: 86-432-64678411

Fax: 86-432-64665812

Web Site: [www.hwdz.com.cn](http://www.hwdz.com.cn)